

Electronic Patent Application Fee Transmittal

Application Number:	10718192			
Filing Date:	20-Nov-2003			
Title of Invention:	Heat spreader ball grid array (HSBGA) design for low-k integrated circuits (IC)			
First Named Inventor:	Yian-Liang Kuo			
Filer:	Daniel R. McClure			
Attorney Docket Number:	TS03-336			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790